

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
29 July 2004 (29.07.2004)

PCT

(10) International Publication Number
WO 2004/062853 A1

(51) International Patent Classification⁷: **B24D 13/14**,
B24B 37/04, B24D 13/12

(21) International Application Number:
PCT/US2003/036487

(22) International Filing Date:
17 November 2003 (17.11.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10/339,963 10 January 2003 (10.01.2003) US

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(81) Designated States (*national*): AE, AG, AL, AM, AT (utility model), AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ (utility model), CZ, DE (utility model), DE, DK (utility model), DK, DM, DZ, EC, EE (utility model), EE, EG, ES, FI (utility model), FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK (utility model), SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW.

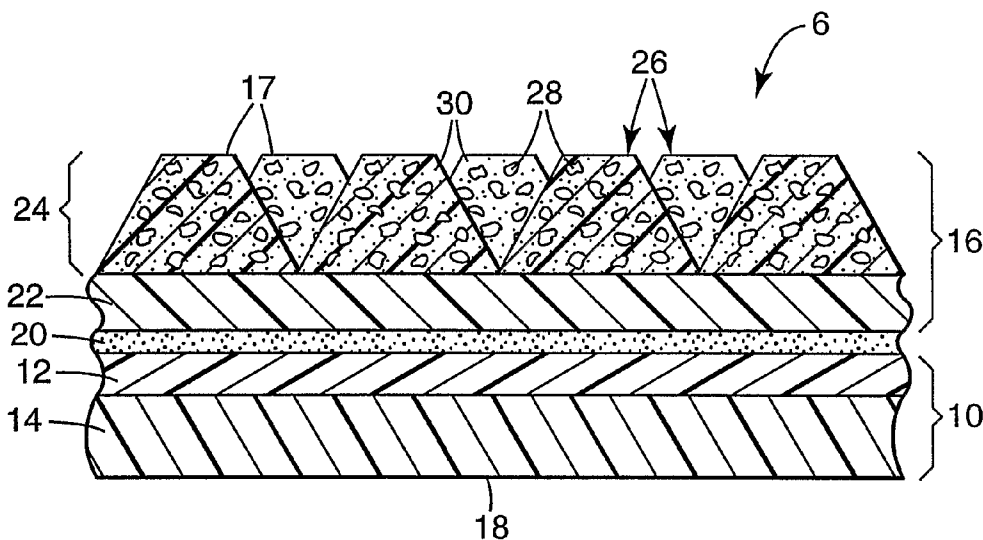
(84) Designated States (*regional*): ARIPO patent (BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

— *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii)) for all designations*

[Continued on next page]

(54) Title: METHOD OF USING A SOFT SUBPAD FOR CHEMICAL MECHANICAL POLISHING



(57) Abstract: The present invention is directed to a method of modifying a wafer surface comprising providing a first abrasive article (6) comprising a first three-dimensional fixed abrasive element (16) and a first subpad (10) generally coextensive with the first fixed abrasive element (16), contacting a surface of the first three-dimensional fixed abrasive element (16) with a wafer surface, and relatively moving the first abrasive article (6) and the wafer. The method additionally provides providing a second abrasive article (6) comprising a second three-dimensional fixed abrasive element (16) and a second subpad (10) generally coextensive with the second fixed abrasive element (16), contacting a surface of the second three-dimensional fixed abrasive element (16) with the wafer surface, and relatively moving the second abrasive article (6) and the wafer. Wherein the first subpad (10) has a deflection less than the deflection of the second subpad (10) when measured 1.5 cm from the edge of a 1 kg weight, the weight having a contact area of 1.9 cm diameter.

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— *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii)) for all designations*

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Published:

— *with international search report*